

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	967	361/777.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/16 15:53
S2	16	APPARATUS near MOUNTING and MODEM and CARRIER near ASSEMBLY	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/16 15:53
S4	2	S2 and solder	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/16 15:54
S6	120059	("carrier assembly" or "motherboard" or "printed circuit board")	USPAT	OR	ON	2008/08/16 16:14
S7	93	S6 and modem and solder adj pads	USPAT	OR	ON	2008/08/16 16:15
S8	62	S6 and "tip/ring"	USPAT	OR	ON	2008/08/16 16:16
S9	314192	S8 and sold\$4 pads	USPAT	OR	ON	2008/08/16 16:16
S10	0	S8 and sold\$4 near pads	USPAT	OR	ON	2008/08/16 16:17
S11	1	S8 and sold\$4 and pads	USPAT	OR	ON	2008/08/16 16:17
S13	24	("carrier assembly" or "motherboard" or "printed circuit board") and ("solder pads" or pads or soldering) and ("tip/ring")	USPAT	OR	ON	2008/08/16 16:19
S15	18	("carrier assembly" or "motherboard" or "printed circuit board") and ("solder pads" or pads or soldering) and ("tip/ring")and ("Modem")	USPAT	OR	ON	2008/08/16 16:23

S16	18	("carrier assembly" or "motherboard" or "printed circuit board") and ("tip/ring") and ("Modem") and ("solder pads" or pads or soldering)	USPAT	OR	ON	2008/08/16 16:25
S18	120059	("carrier assembly" or "motherboard" or "printed circuit board")	USPAT	OR	ON	2008/08/16 16:32
S19	258	S18 and tip near ring and Modem	USPAT	OR	ON	2008/08/16 16:33
S20	5	S19 and solder adj pads	USPAT	OR	ON	2008/08/16 16:33
S21	63	S19 and pads	USPAT	OR	ON	2008/08/16 16:37
S22	31	S21 and telephone adj line	USPAT	OR	ON	2008/08/16 16:38
S23	8	S22 and IC	USPAT	OR	ON	2008/08/16 16:39
S24	15	S22 and ("IC" or "integrated circuit")	USPAT	OR	ON	2008/08/16 16:40
S30	86	fabrica\$3 near\$3 modem	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/17 15:32
S31	34	method and S30	USPAT	OR	ON	2008/08/17 15:32
S32	6	S31 and ("carrier assembly" or "motherboard" or "printed circuit board")	USPAT	OR	ON	2008/08/17 15:32
S35	2120	("carrier assembly" or "motherboard" or "printed circuit board") and Modem and circui\$4 and pads	USPAT	OR	ON	2008/08/17 16:23
S36	8552	("carrier assembly" or "motherboard" or "printed circuit board") and Modem and circui\$4 and pads and interfac\$3 with telephone adj line	USPAT	OR	ON	2008/08/17 16:25
S37	113	("carrier assembly" or "motherboard" or "printed circuit board") and Modem and circui\$4 and pads and interfac\$3 with telephone adj line and "tip/ring"	USPAT	OR	ON	2008/08/17 16:25

S38	1	("carrier assembly" or "motherboard" or "printed circuit board") and Modem and circui\$4 and padsand interfac\$3 with telephone adj line and "tip/ring" and motherboard	USPAT	OR	ON	2008/08/17 16:25
S39	16	("5384808" "5654984" "5737397" "6067583" "6122216" "6169475" "6169801" "6173405" "6182893" "6212263" "6285706" "6351530" "6401152" "6427011" "6697464" "6876742").PN. OR ("7330544").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/17 16:27
S40	4	"6876742"	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/17 16:33
S41	2	("6876742").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/17 16:33
S42	2	("5654984").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/17 16:52
S43	2	("20040095719").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/18 10:56
S44	2	("20030169567").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/18 10:57
S45	2	("6888725").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/18 10:57
S46	2	("20020159237").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/18 10:58

S47	2813	174/260.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/19 09:10
S48	2	"20080023815"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/19 09:15
S49	3	10/557206	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/19 09:15
S50	8108	core near substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/19 09:49
S51	97	S47 and S50	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/19 09:49
S53	234620	yamada.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/19 09:56
S58	91	Yamada.in. and first adj core	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/19 10:09
S59	8	S58 and insulating adj layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/19 10:09
S60	10267	conductor adj layer and insulating adj layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/19 11:36

S61	349	conductor adj layer and insulating adj layer and multilayer adj printed adj wiring	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/19 11:38
S62	210	conductor adj layer and insulating adj layer and multilayer adj printed adj wiring and "thickness"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/19 11:39
S63	14069	insula\$3 adj layer and conduct\$3 near layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/19 12:33
S64	30167	insula\$3 near2 layer and conduct\$3 near layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/19 12:33
S66	79	S64 and substrate and multilayer adj printed adj wiring adj board	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/19 12:35
S67	1145	@ad<="20020809" and substrate and multilayer adj printed adj wiring adj board	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/19 12:37
S68	202	@ad<="20020809" and conductor adj layer and insulating adj layer and multilayer adj printed adj wiring	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/19 12:41
S69	57454	"electro-optical"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/19 13:16
S70	27691	S69 and display	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/19 13:16

S71	123	S70 and flexible adj printed adj circuit adj board	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/19 13:17
S72	4	S71 and "multi-layer"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/19 13:17
S73	2	"20050088830"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/19 13:20
S77	5	("2004033476").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/19 13:24
S78	1091	(361/749).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/19 13:25
S79	158	S78 and flexible adj printed adj circuit adj board	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/19 13:25
S80	16	("4025896" "5103375" "5159751" "5170326" "5179501" "5216581" "5250845" "5265322" "5386341" "5434362" "5969945" "5998738" "6292370").PN. OR ("6501661").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/19 13:34
S81	60	"5,229,916"	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/19 14:07
S82	2	("5,229,916").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/19 14:07

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